



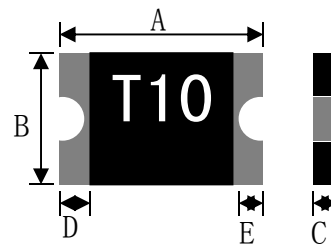
深圳市万瑞和电子有限公司
SHENZHEN WONDHOPE ELECTRIC CO., LTD

地址 (Add): 深圳市龙华区观澜街道观光路美泰科技园1栋 1nd Bldg, Meitai Industrial Zone, Guanguang Road, Guanlan, Longhua, Shenzhen, China	封装 (package): SMD 1206 型号 (Model): 100 最大电压 (V_{max}): 12V
电话 (Tel): 86-0755-29503668 29503690 29503691	最大电流 (I_{max}): 100A
传真 (Fax): 86-0755-29503998 邮编 (P.C.): 518131	
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产品规格书 Specification Sheet

产品标识/Marking:

T10: 产品型号标识/Part identification



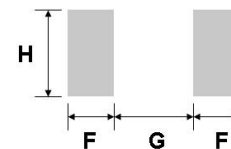
产品外形尺寸
/Appearance
and size of
production

焊点可焊性/Solderability:

符合EIA规定RS186-9E 和 ANSI/J-STD-002
第3类标准/Meets EIA specification
RS186-9E and ANSI/J-STD-002 Category 3

焊点材料/Terminal Pad Materials:

无铅镀锡的镀镍铜箔/Sn-plated nickel-copper, lead-free device.



推荐焊盘设计
/Recommended
pad layout

产品尺寸/Dimensions:

UNIT	A		B		C		D	E	F	G	H
	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MIN			
mm	3	3.5	1.5	1.8	0.5	1.3	0.15	0.1	1	2	1.9
inch	0.12	0.14	0.06	0.07	0.020	0.050	0.006	0.004	0.04	0.08	0.07

电气特性/Performance Specification:

Model	V_{max} (V_{dc})	I_{max} (A)	I_{hold} @25°C (A)	I_{trip} @25°C (A)	P_d Tpy. (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	R _{imin} (Ω)	R _{1max} (Ω)
SMD100	12	100	1.00	2.00	0.8	8.0	0.30	0.050	0.280

V_{max} : 产品在规定电流下工作不被破坏的最大电压;

/Maximum voltage, device can withstand without damage at rated current;

I_{max} : 产品在规定电压下工作不被破坏的最大电流;

/Maximum fault current, device can withstand without damage at rated voltage;

I_{hold} : 产品在25°C静止空气中30分钟不动作的最大工作电流;

/Hold Current, device will sustain for 30min without tripping in 25°C still air;

I_{trip} : 产品在25°C静止空气中动作的最小电流;

/Minimum current at which the device will trip in 25°C still air;

P_d : 产品在25°C静止空气中保护状态中消耗的功率;

/Power dissipated from device when in the tripped state in 25°C still air;

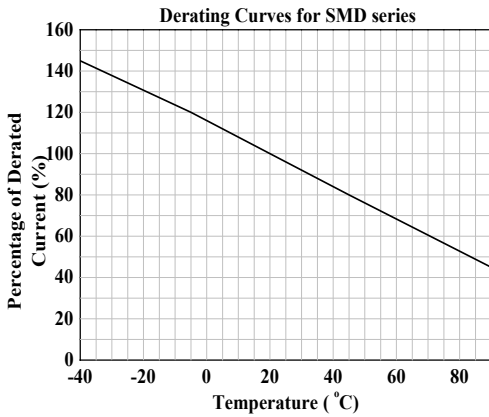
$R_{i\min}$: 满足功能要求的最小成品电阻值;

/Minimum resistance of device in initial (un-soldered) state;

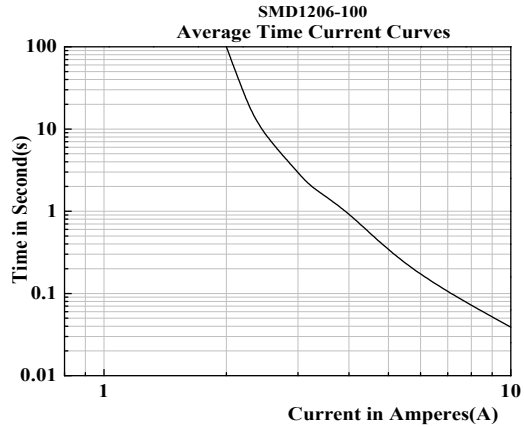
$R_{1\max}$: 焊接完1小时, 产品在25°C静止空气中的最大电阻值。

/Maximum resistance of device at 25°C measured one hour post reflow.

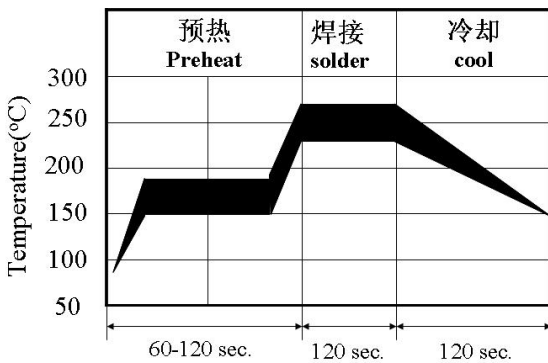
电流折减与环境温度曲线图
/Average Time Current Curve



25°C时动作时间曲线图
/Average Time Current Curve at 25°C



回流焊接条件/Solder reflow conditions



注意: 如果回流焊温度超过图表建议最高温度 (260°C), 元件可能损坏而达不到规范要求.

/Note: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

储存与放置/Storage and Handling

储存条件: 低于30 °C, 相对湿度小于60%. 如果超出储存条件, 元件可能达不到规范要求. /Storage conditions: 30°C max, 60% R.H.Devices may not meet specified performance if storage conditions are exceeded.

订购须知/Order Information

T10=产品标识 /Part identification, SMD1206=封装尺寸/ Packaging, 100=产品型号 /Model
包装数量3500个/盘 3500pcs/Reel

注意事项/ WARNING:

- 1、超出额定范围或不正确地使用PPTC元件都可能导致产品的损坏, 并可能导致电弧和火焰; /Use PPTC exceed by the maximum rating and improper use may result in device damage and possible electrical arcing and flame.
- 2、PPTC元件一般只用于偶然的过流或超温故障时的保护, 切勿用于故障频繁发生或预期会发生长时间故障的场合; /PPTC are designed for protection against over current or temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- 3、如果不按照建议安装、测试和使用产品, 元件性能可能会受到不利影响; /Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- 4、在电感强度大的电路中使用, 可能会产生超过PPTC元件的额定电压的回路电压; /Use PPTC with a large inductance in circuit will generate a circuit voltage above the rated voltage of the PPTC.
- 5、PPTC元件应用时不能长期处于压力下, 使其缺乏膨胀空间而影响其性能, 如处于高压或安装在受限的狭小空间里. /Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- 6、由于上述原因造成的质量问题, 我司概不负责. /If any quality problems caused by improper use mentioned above,our company is not responsible.

- 1、建议回流方法: 红外线、蒸汽炉、热空气炉; /Recommended reflow methods: IR, vapor phase oven, hot air oven.
- 2、使用于波焊制程时, 不可将元件置于电路板之背面/底面; /Devices are not designed to be wave soldered to the bottom side of the board.
- 3、建议焊锡膏涂抹厚度最大为0.25mm/0.010 inch; /Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- 4、元件可使用一般业界标准程序和溶剂来实施清洁. /Devices can be cleaned using standard method and solvents.